

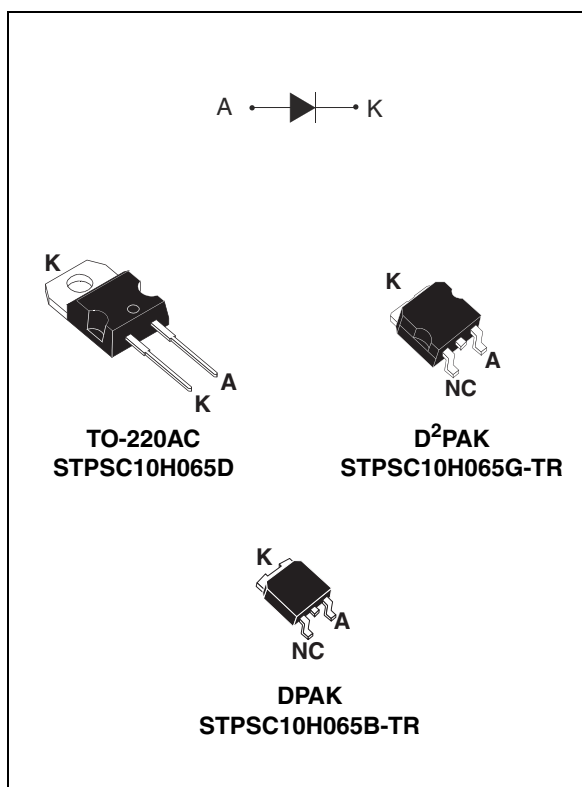
### Features

- No or negligible reverse recovery
- Switching behavior independent of temperature
- Dedicated to PFC applications
- High forward surge capability

### Description

The SiC diode is an ultrahigh performance power Schottky diode. It is manufactured using a silicon carbide substrate. The wide bandgap material allows the design of a Schottky diode structure with a 650 V rating. Due to the Schottky construction, no recovery is shown at turn-off and ringing patterns are negligible. The minimal capacitive turn-off behavior is independent of temperature.

Especially suited for use in PFC applications, this ST SiC diode will boost the performance in hard switching conditions. Its high forward surge capability ensures a good robustness during transient phases.



**Table 1. Device summary**

Symbol	Value
$I_{F(AV)}$	10 A
$V_{RRM}$	650 V
$T_j$ (max)	175 °C

# 1 Characteristics

**Table 2. Absolute ratings (limiting values at 25 °C unless otherwise specified)**

Symbol	Parameter		Value	Unit
V <sub>RRM</sub>	Repetitive peak reverse voltage		650	V
I <sub>F(RMS)</sub>	Forward rms current		22	A
I <sub>F(AV)</sub>	Average forward current	T <sub>c</sub> = 120 °C, δ = 0.5	10	A
I <sub>FSM</sub>	Surge non repetitive forward current	t <sub>p</sub> = 10 ms sinusoidal, T <sub>c</sub> = 25 °C	90	A
		t <sub>p</sub> = 10 ms sinusoidal, T <sub>c</sub> = 125 °C	80	
		t <sub>p</sub> = 10 μs square, T <sub>c</sub> = 25 °C	470	
I <sub>FRM</sub>	Repetitive peak forward current	T <sub>c</sub> = 120 °C, T <sub>j</sub> = 150 °C, δ = 0.1	36	A
T <sub>stg</sub>	Storage temperature range		-55 to +175	°C
T <sub>j</sub>	Operating junction temperature <sup>(1)</sup>		-40 to +175	°C

1.  $\frac{dP_{tot}}{dT_j} < \frac{1}{R_{th(j-a)}}$  condition to avoid thermal runaway for a diode on its own heatsink

**Table 3. Thermal resistance (typical values)**

Symbol	Parameter	Value		Unit
		Typ.	Max.	
R <sub>th(j-c)</sub>	Junction to case	1.25	1.5	°C/W

**Table 4. Static electrical characteristics**

Symbol	Parameter	Tests conditions	Min.	Typ.	Max.	Unit	
I <sub>R</sub> <sup>(1)</sup>	Reverse leakage current	T <sub>j</sub> = 25 °C	V <sub>R</sub> = V <sub>RRM</sub>	-	9	100	μA
		T <sub>j</sub> = 150 °C		-	85	425	
V <sub>F</sub> <sup>(2)</sup>	Forward voltage drop	T <sub>j</sub> = 25 °C	I <sub>F</sub> = 10 A	-	1.56	1.75	V
		T <sub>j</sub> = 150 °C		-	1.98	2.5	

1. t<sub>p</sub> = 10 ms, δ < 2%

2. t<sub>p</sub> = 500 μs, δ < 2%

To evaluate the conduction losses use the following equation:

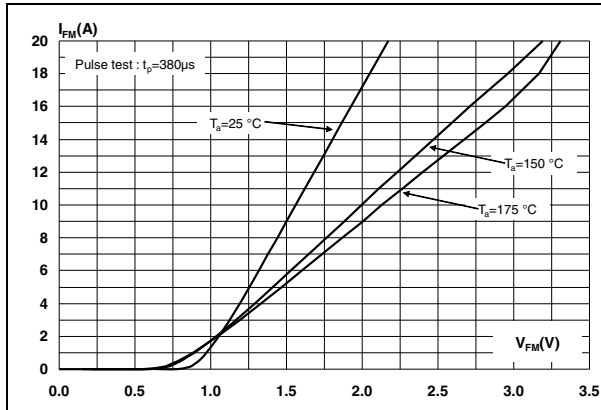
$$P = 1.35 \times I_{F(AV)} + 0.115 \times I_{F(RMS)}^2$$

**Table 5. Dynamic electrical characteristics**

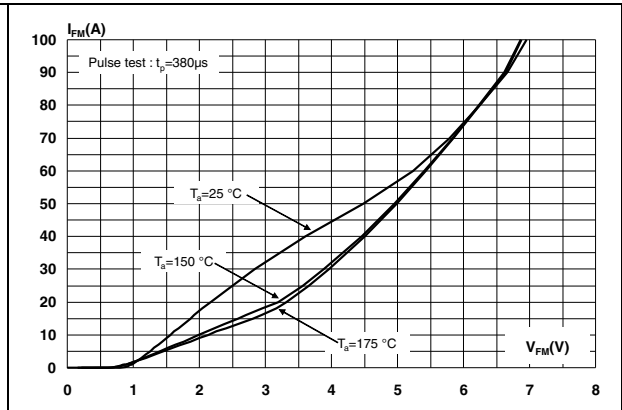
Symbol	Parameter	Test conditions	Typ.	Unit
Q <sub>cj</sub> <sup>(1)</sup>	Total capacitive charge	V <sub>R</sub> = 400 V,	28.5	nC
C <sub>j</sub>	Total capacitance	V <sub>R</sub> = 0 V, T <sub>c</sub> = 25 °C, F = 1 MHz	480	pF
		V <sub>R</sub> = 400 V, T <sub>c</sub> = 25 °C, F = 1 MHz	48	

1. Most accurate value for the capacitive charge:  $Q_{cj} = \int_0^{V_{OUT}} C_j(V_R) \cdot dV_R$

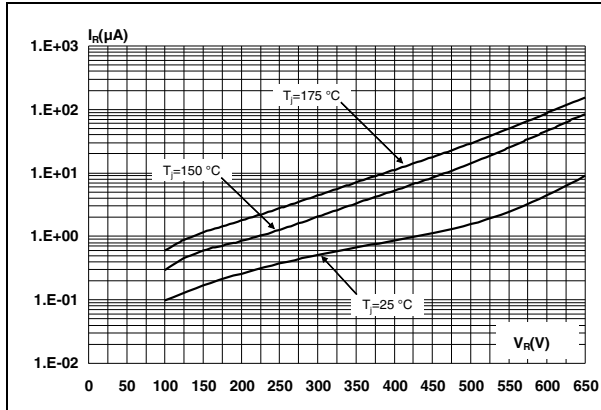
**Figure 1. Forward voltage drop versus forward current (typical values, low level)**



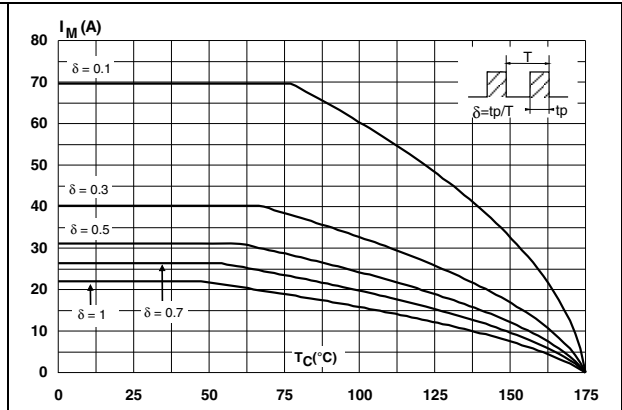
**Figure 2. Forward voltage drop versus forward current (typical values, high level)**



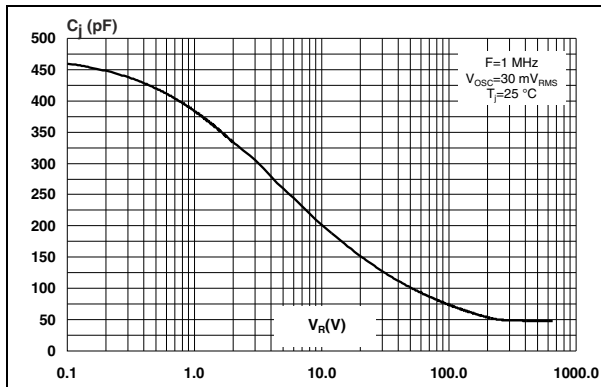
**Figure 3. Reverse leakage current versus reverse voltage applied (typical values)**



**Figure 4. Peak forward current versus case temperature**



**Figure 5. Junction capacitance versus reverse voltage applied (typical values)**



**Figure 6. Relative variation of thermal impedance junction to case versus pulse duration**

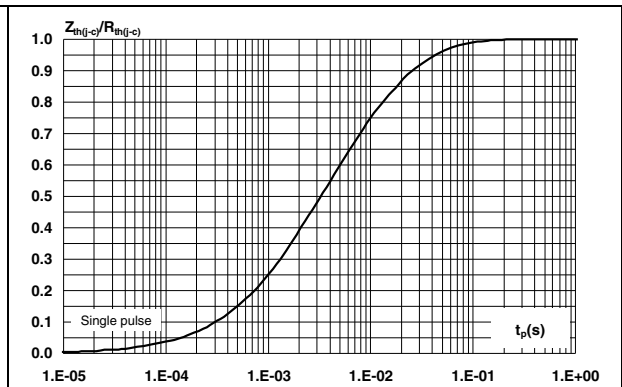


Figure 7. Non-repetitive peak surge forward current versus pulse duration (sinusoidal waveform)

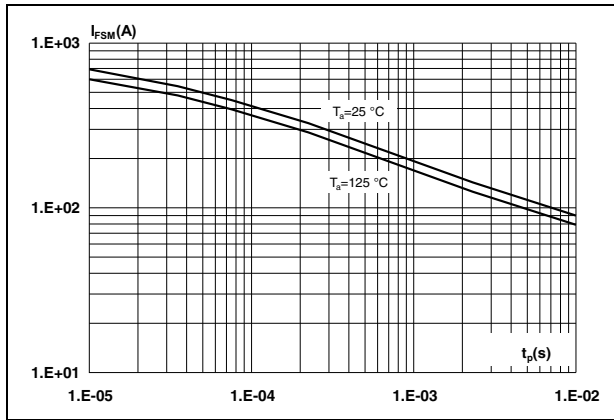
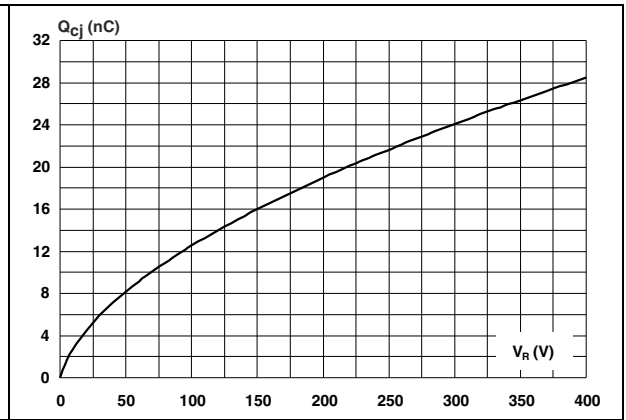


Figure 8. Total capacitive charges versus reverse voltage applied (typical values)



## 2 Package information

- Epoxy meets UL94, V0
- Recommended torque value (TO-220AC): 0.4 to 0.6 N·m
- Cooling method: conduction (C)

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**Table 6. TO-220AC dimensions**

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.40	4.60	0.173	0.181
C	1.23	1.32	0.048	0.051
D	2.40	2.72	0.094	0.107
E	0.49	0.70	0.019	0.027
F	0.61	0.88	0.024	0.034
F1	1.14	1.70	0.044	0.066
G	4.95	5.15	0.194	0.202
H2	10.00	10.40	0.393	0.409
L2	16.40 typ.		0.645 typ.	
L4	13.00	14.00	0.511	0.551
L5	2.65	2.95	0.104	0.116
L6	15.25	15.75	0.600	0.620
L7	6.20	6.60	0.244	0.259
L9	3.50	3.93	0.137	0.154
M	2.6 typ.		0.102 typ.	
Diam. I	3.75	3.85	0.147	0.151

Table 7. DPAK dimensions

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	2.20	2.40	0.086	0.094
A1	0.90	1.10	0.035	0.043
A2	0.03	0.23	0.001	0.009
B	0.64	0.90	0.025	0.035
B2	5.20	5.40	0.204	0.212
C	0.45	0.60	0.017	0.023
C2	0.48	0.60	0.018	0.023
D	6.00	6.20	0.236	0.244
E	6.40	6.60	0.251	0.259
G	4.40	4.60	0.173	0.181
H	9.35	10.10	0.368	0.397
L2	0.80 typ.		0.031 typ.	
L4	0.60	1.00	0.023	0.039
V2	0°	8°	0°	8°

Figure 9. Footprint (dimensions in mm)

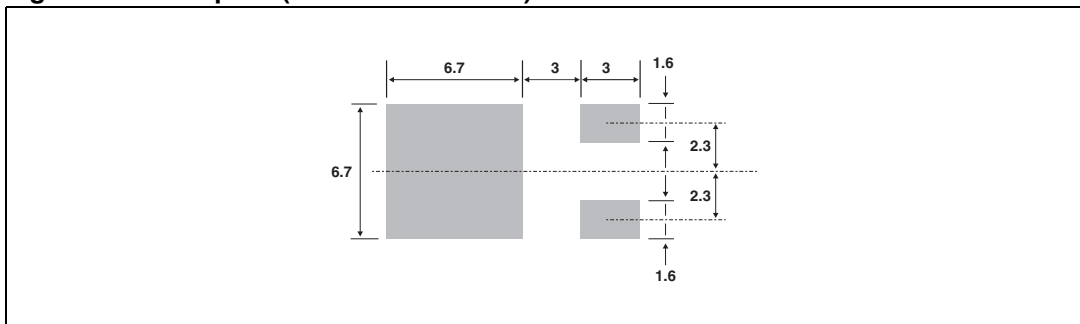
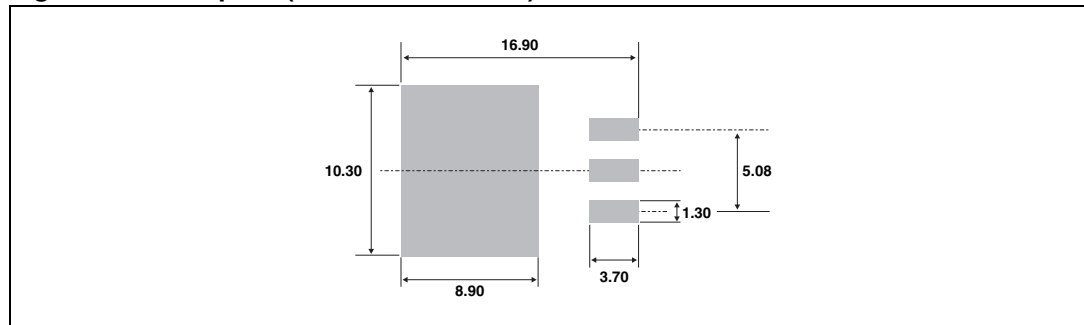


Table 8. D<sup>2</sup>PAK dimensions

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.40	4.60	0.173	0.181
A1	2.49	2.69	0.098	0.106
A2	0.03	0.23	0.001	0.009
B	0.70	0.93	0.027	0.037
B2	1.14	1.70	0.045	0.067
C	0.45	0.60	0.017	0.024
C2	1.23	1.36	0.048	0.054
D	8.95	9.35	0.352	0.368
E	10.00	10.40	0.393	0.409
G	4.88	5.28	0.192	0.208
L	15.00	15.85	0.590	0.624
L2	1.27	1.40	0.050	0.055
L3	1.40	1.75	0.055	0.069
M	2.40	3.20	0.094	0.126
R	0.40 typ.		0.016 typ.	
V2	0°	8°	0°	8°

Figure 10. Footprint (dimensions in mm)



### 3 Ordering information

**Table 9. Ordering information**

Order code	Marking	Package	Weight	Base qty	Delivery mode
STPSC10H065D	STPSC10H065D	TO-220AC	1.86 g	50	Tube
STPSC10H065G-TR	STPSC10H065G	D <sup>2</sup> PAK	1.48 g	1000	Tape and reel
STPSC10H065B-TR	STPSC 10H065	DPAK	0.32 g	2500	Tape and reel

### 4 Revision history

**Table 10. Document revision history**

Date	Revision	Changes
31-Aug-2012	1	First issue.
10-Oct-2012	2	Added Max. value to <a href="#">Table 3</a> .



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